



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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版数 REV.	年月日 DATE	DON NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	24.Nov.2005	058588	ADDED NEW ITEMS		K.INOUE		<i>Ot. Hashiguchi</i>

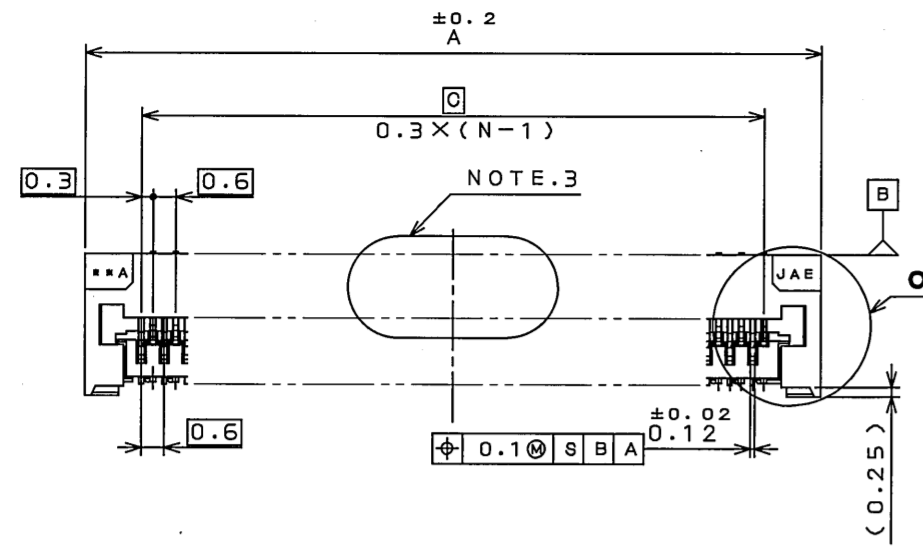
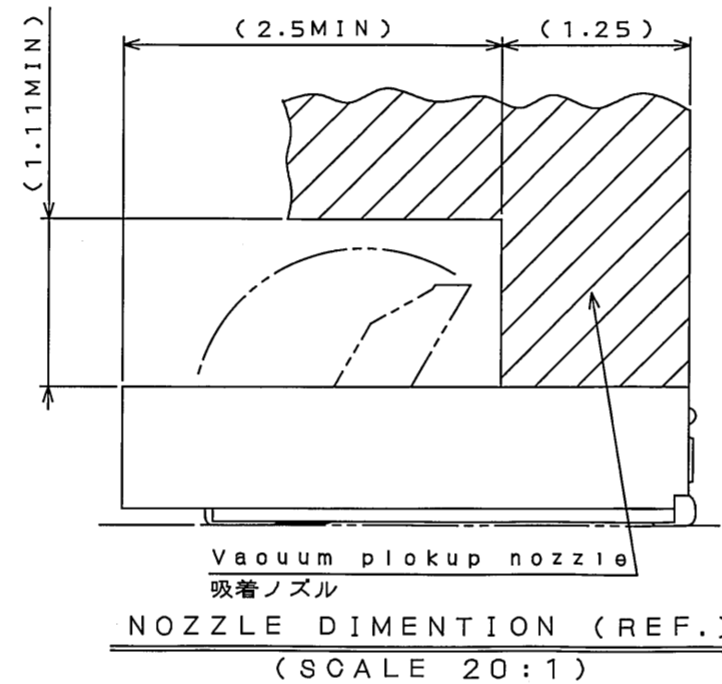
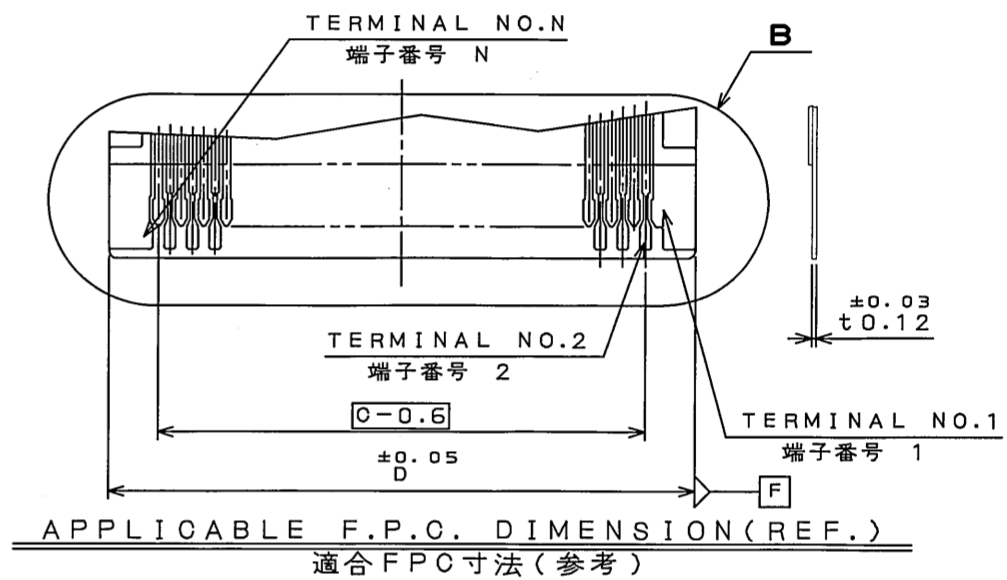
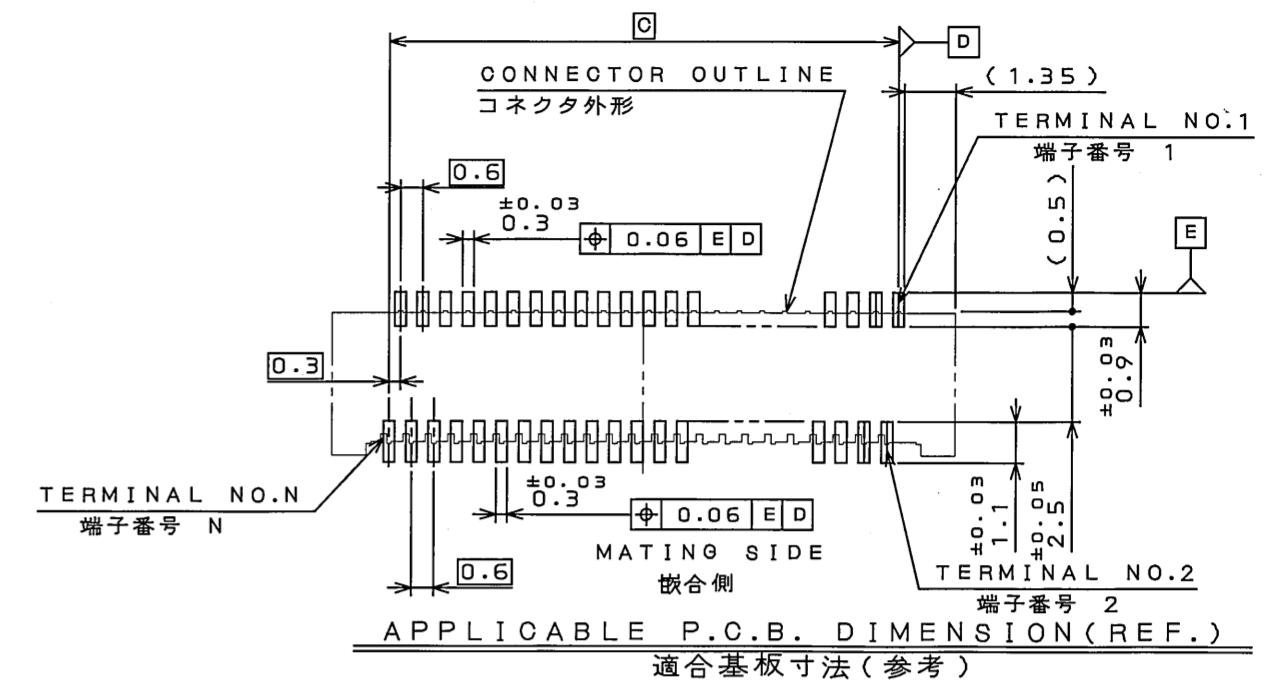


TABLE 1

PRODUCT NO. 品名	A	B	C	D
FF02860SV1	20.7	19.81	17.7	19.74
FF02850SV1	17.7	16.81	14.7	16.74
FF02840SV1	14.7	13.81	11.7	13.74

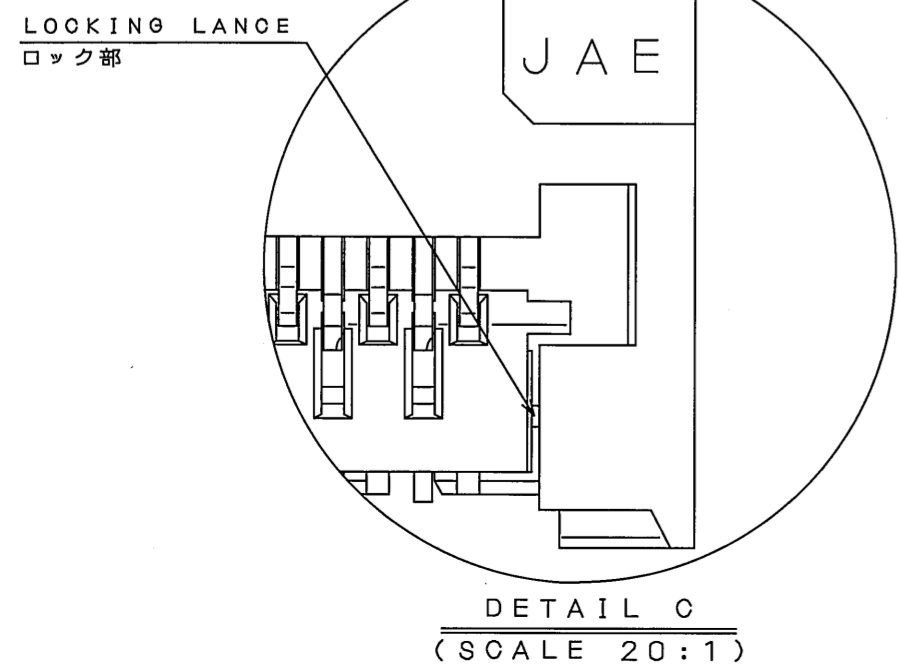
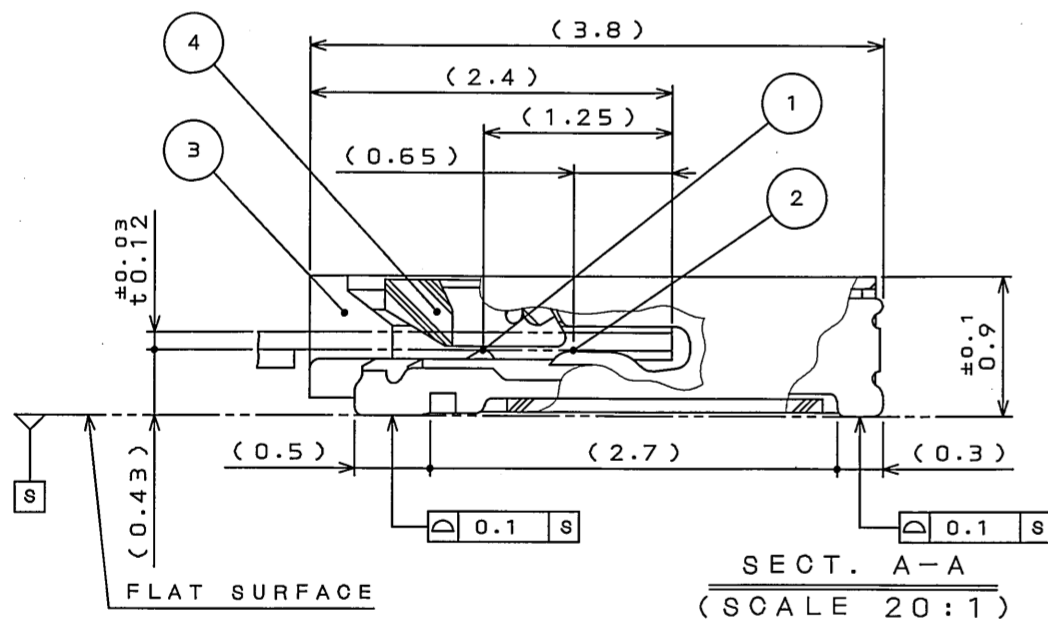
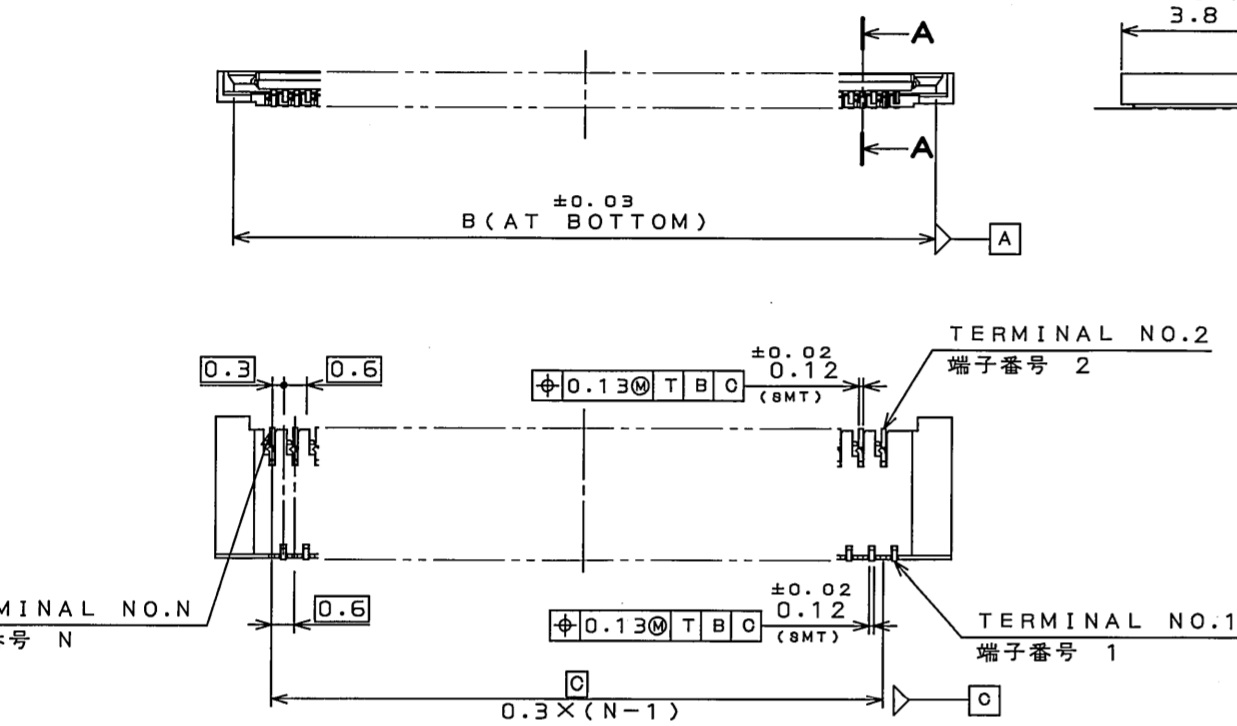
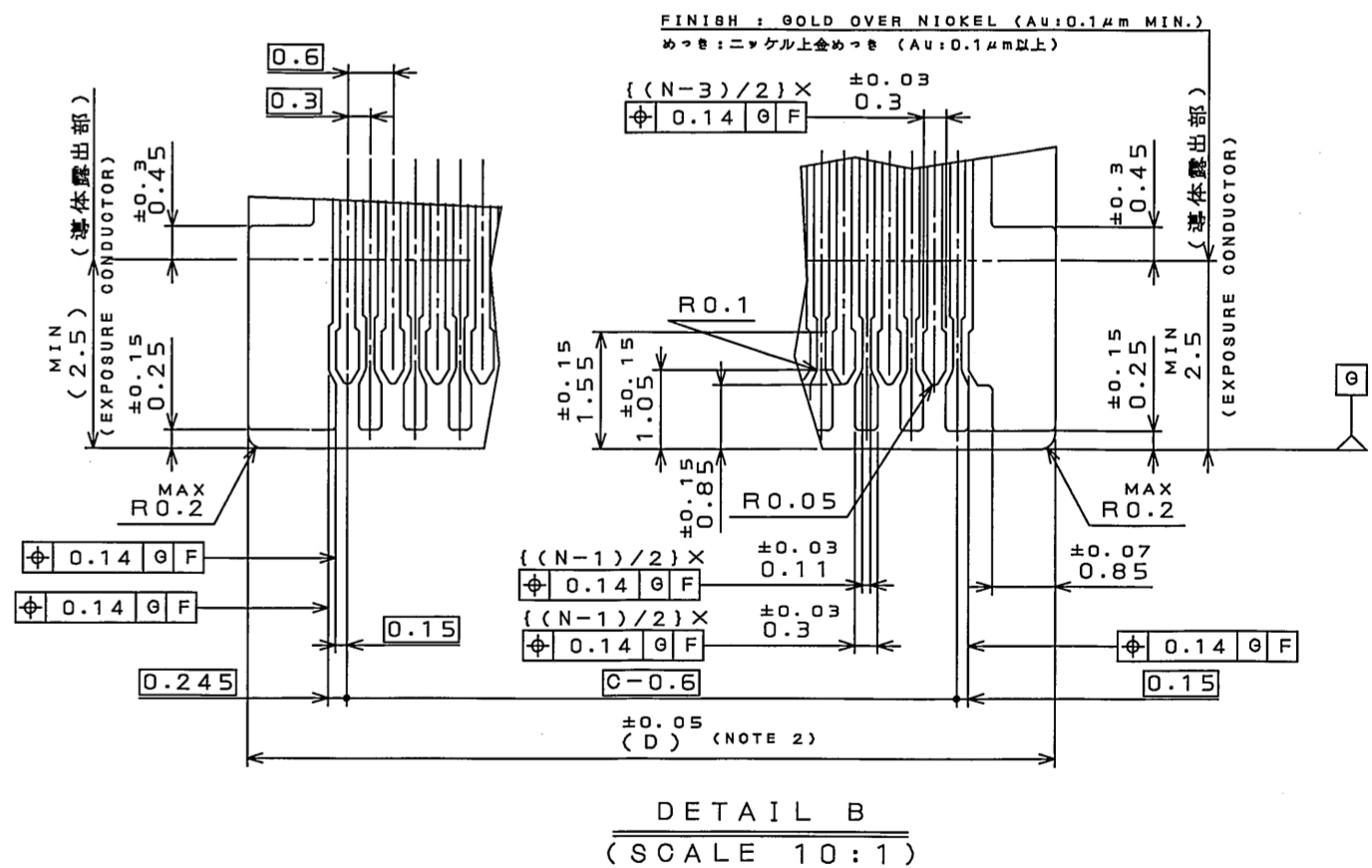


NOTE 1. REFER TO TABLE 2 ABOUT RECOMMENDED FPC COMPOSITION.  
 NOTE 2. TOLERANCE OF DIMENSION D IS RECOMMENDED TO BE  $\pm 0.05$  IN ORDER TO IMPROVE PRECISION OF PITCH POSITIONING AND CONNECTION RELIABILITY.  
 NOTE 3. LOT NUMBER IS MARKED ON THE TOP CENTER PORTION OF THE CONNECTOR.

注1. 推奨FPC構成はTABLE2参照のこと。  
 注2. 寸法Dはピッチ方向の位置決め精度を高め接触信頼性を高めるために  $\pm 0.05$  を推奨する。  
 注3. ロット番号がコネクタ上面中央部に表記される。

TABLE 2

COMPOSITION 層名		RECOMMENDED 推奨
GOLD PLATING 金めっき	ELECTROLYSIS PLATING 電解めっき	0.1 $\mu$ m MIN
NICKEL PLATING ニッケルめっき	ELECTROLYSIS PLATING 電解めっき	SOFT TYPE IF AVAILABLE
COPPER 銅箔	ROLLED MATERIAL 圧延銅	NOMINAL 18 $\mu$ m MAX
ADHESIVE 接着剤	THERMOSETTING ADHESIVE 熱硬化性	NONE (RECOMMENDED)
BASE FILM ベースフィルム	POLYIMIDE ポリイミド	25 $\mu$ m
ADHESIVE 接着剤	THERMOSETTING ADHESIVE 熱硬化性	30 $\mu$ m MAX
REINFORCE PLATE 補強板	POLYIMIDE ポリイミド	



4	ACTUATOR アクチュエータ	1	PPS		COLOR:BLACK/色相:黒 UL94V-0
3	BASE INSULATOR ベースインシュレータ	1	LCP		COLOR:WHITE/色相:白 UL94V-0
2	CONTACT 2 コンタクト 2	N	COPPER ALLOY 銅合金		
1	CONTACT 1 コンタクト 1	N	COPPER ALLOY 銅合金		
符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
仕様書 (SPECIFICATION)	JAOS-10293-*	第1版 (ORIGINAL DATE) 14.Jul.2005	尺 (SCALE) 5:1	シリーズ (SERIES) FF02S	日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
公差 (GENERAL TOLERANCE)		製図 DR.	担当 CHK. K.INOUE	名称 (TITLE) FF02S * SV1	図面番号 (DRAWING NO.) SJ104400
寸法 (DIMENSION)	角度 (ANGLES)	査閲 APPD.	承認 APPD. O.HASHIGUCHI	(EVEN NUMBER OF CONTACTS) (偶数芯数)	
. ±0.8	° ±			質量 (MASS)	
.X ±0.4	°X ±				版数 (REV.) 2
.XX ±0.1					
.XXX ±					